

# Bill of Materials

	SCM	SCC	Remarks
Die Attach	Hitachi EN4900	Hitachi EN4900	Same BOM
Wire type	Gold MKE UR2	Gold MKE UR2	
Mold Compound	Hitachi CEL9220	Hitachi CEL9220	
Lead Finish	NiPdAu	NiPdAu	

# Qualification Results Summary for LFCSP Package in NiPdAu Pre-plated Leadframe at STATS ChipPAC China (SCC)

QUALIFICATION RESULTS			
Test	Specifications	Sample Size	Result
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	<b>3 x 77</b>	<b>PASS</b>
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	<b>3 x 11</b>	<b>PASS</b>
Low Temperature Storage (LTS)	JEDEC <i>JESD22-A119</i>	<b>3 x 77</b>	<b>PASS</b>
Field Induced Charged Device Model (FICDM)	JEDEC <i>JESD22-C101</i>	<b>3/Voltage</b>	<b>PASS ±1250V</b>

\*Preconditioned per JEDEC/IPC J-STD-020